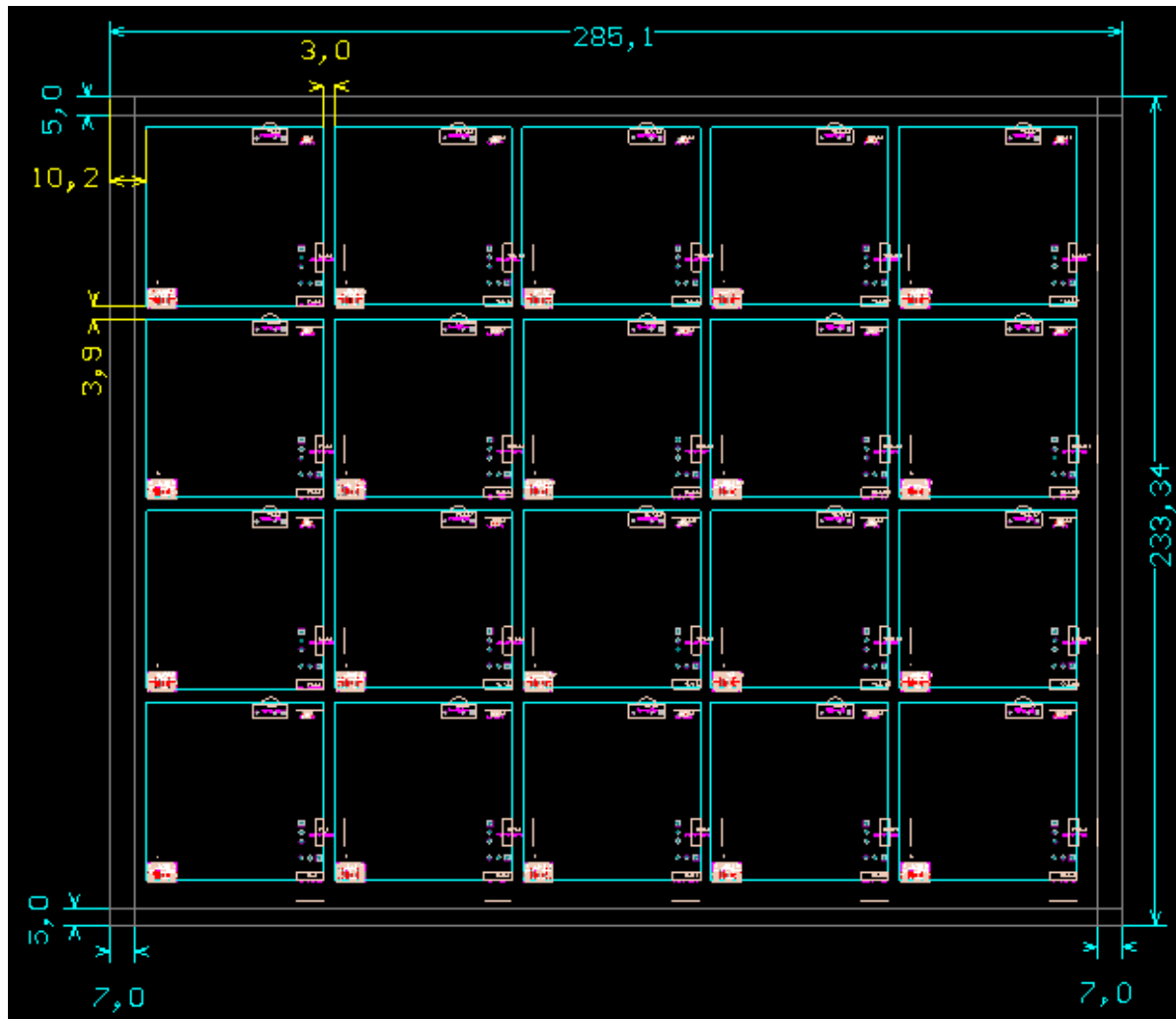


Panelisation setup 1 of 1

- See file PCB requirement_R03.PDF for locations of ICT holes and panel fiducials top/bottom side.
- There are to be no v-cuts in this panel.
- Grey lines for border indication only.
- Do **not** place any mouse-bites (small drill holes) in the break-bridges



Specials 1 of 1 : Silkscreen printing

There is to be silkscreen printing on the top layer of the PCB. See file: *.GM3

There is to be silkscreen printing on the bottom layer of the PCB. See file: *.GM4

Board / Plating specifications

Thickness of NI/AU:

Phosphorus Nickel (Ni) as a diffusion barrier.

Thickness : 3 - 6 micron.

Top layer : soft gold (Au).

Thickness : 0.06 - 0,10 micron

Finished board thickness:

Final board thickness = 1.6mm;

All copper layers should be 35u thick copper.

FR-4

For the used PCB materials (core material / pre-preg / copperfoil etc) the minimal compliance should be to IPC-4101.

- Flammability : UL94V-0
- Tg C°>= 110°
- Dk @ 1Mhz <= 5.4

Panel information

Feed Direction Arrow, Text "Top", Box outline, PN-number; allowed in copper but only in panelisation border